

Data sheet acquired from Harris Semiconductor SCHS069

Vcc VDD 16 15 2 FOUT Aout 3 14 FIN AIN BOUT 4 13 SELECT BIN 5 12 FOUT EIN Cout 6 П CIN •Роит 7 10 ¥38 ċ DIN VIEW TOP 9205-39308 TERMINAL ASSIGNMENT

CMOS Hex Voltage-Level Shifter for TTL-to-CMOS or CMOS-to-CMOS Operation

High-Voltage Types (20-Volt Rating) Features:

- Independence of power-supply sequence considerations-Vcc can exceed Vpb; input signals can exceed both Vcc and Vob
- Up and down level-shifting capability
- Shiftable input threshold for either CMOS or TTL compatibility
- Standardized symmetrical output
- characteristics

CD4504B hex voltage level-shifter consists of six circuits which shift input signals from the Vcc logic level to the Vpp logic level. To shift TTL signals to CMOS logic levels, the SELECT input is at the Vcc HIGH logic state. When the SELECT input is at a LOW logic state, each circuit translates signals from one CMOS level to another.

100% tested for guiescent current @ 20 V

CD4504B Types

- Maximum input current of 1 µA at 18 V. over full package-temperature range; 100 nA at 18 V and 25° C
- 5 V, 10 V, and 15 V parametric ratings Meets all requirements of JEDEC
- Standard No. 13B, "Standard Specifications for Description of 'B' Series **CMOS** Devices"

The CD4504B device is supplied in 16-lead ceramic dual-inline packages (D and F suffixes), 16-lead plastic dual-in-line packages (E suffix), 16-lead dual-in-line surface-mount plastic packages (M suffix), and in chip form (H suffix).

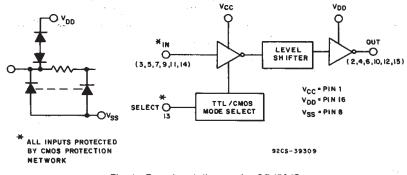


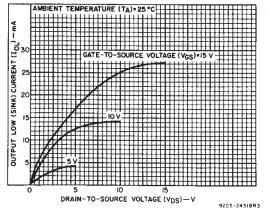
Fig. 1 - Functional diagram for CD4504B.

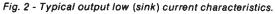
MAXIMUM RATINGS, Absolute-Maximum Values:	
DC SUPPLY-VOLTAGE RANGE, (VDD)	
Voltages referenced to V _{SS} Terminal)	
INPUT VOLTAGE RANGE, ALL INPUTS	0.5V to V _{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT	±10mA
POWER DISSIPATION PER PACKAGE (PD):	
For T _A = -55°C to +100°C	
For T _A = +100°C to +125°C"	erate Linearity at 12mW/ ⁰ C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR T _A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	
OPERATING-TEMPERATURE RANGE (TA)	55°C to +125°C
STORAGE TEMPERATURE RANGE (Tstg)	
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max	

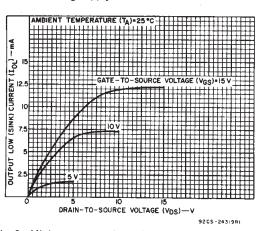
STATIC ELECTRICAL CHARACTERISTICS

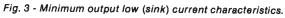
		CONDITIONS				LIMITS AT INDICATED TEMPERATURES (°C)						Τ	
		Vo	Vin	Vcc	VDD					1	+25		1.
CHAR	ACTERISTIC	(V)	(V)	(V)	(V)	-55	-40	+85	+125	MIN	ТҮР	MAX	UNITS
Quiescent Device Current, IDD Max and ICC in CMOS-CMOS Mode			0,5	5	5	1	1	30	30	_	0.02	1	μΑ
			0, 10	5	10	2	2	60	60	_	0.02	2	
			0, 15	5	- 15	4	4	120	120	—	0.02	4	
		-	0,20	5	20	20	20	600	600		0.04	20	
Quiescent Device Current, I _{CC} Max TTL-CMOS Mode		-	0, 5	5	5	5	5	6	6	_	2.5	5	mA
			0, 10	5	10	5	5	6	6		2.5	5	
		-	0,15	5	15	5	5	6	6		2.5	5	1
Output Low (Sink)		0.4	0.5	-	5	0.64	0.61	0.42	0.36	0.51	1	_	
Current, I _{OL} Min	0.5	0,10	-	10	1.6	1.5	1.1	0.9	1.3	2.6	-	1	
		1.5	0, 15		15	4.2	4	2.8	2.4	3.4	6.8		1
Output High		4.6	0,5	-	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	_	mA
Current, I _{OH} Min	2.5	0,5	—	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	_		
	9.5	0, 10	—	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	_		
		13.5	0,15	-	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	_	1
Output Voltage: Low-Level, V _{OL} Max			0,5		5		0.0	05	·	_	0	0.05	†
		-	0,10	-	10	0.05			-	0	0.05		
			0,15	_	15	0.05 — 0		0.05	1				
Output Voltage: High-Level, V _{OH} Min		-	0,5	-	5	4.95			4.95	5	_	1	
		—	0, 10	—	10	9.95			9.95	10	_		
		—	0,15	_	15	14.95			14.95	15	-		
Input Low	TTL-CMOS	1	_	5	10	0.8			_	_	0.8		
Voltage, VII Max	TTL-CMOS	1	—	5	15	0.8 1.5 1.5 3			_		0.8	v	
Note 1	CMOS-CMOS	1	_	5	10				_		1.5		
	CMOS-CMOS	1.5	_	5	15				_		1.5		
	CMOS-CMOS	1.5	_	10	15					<u> </u>	3		
Input High	TTL-CMOS	9	_	5	10	2			2		_		
Voltage,	TTL-CMOS	13.5	_	5	15	2 3.5			2				
V _{IH} Min Note 1	CMOS-CMOS	9	-	5	10				3.5				
	CMOS-CMOS	13.5	_	5	15	3.5			3.5				
	CMOS-CMOS	13.5	—	10	15	7				7	_	_	
Input Current, IIN Max			0,18		18	±0.1	±0.1	±1	±1	_	±10 ⁻⁵	±0.1	μA

Note 1: Applies to the 6 input signals. For mode control (P13), only the CMOS-CMOS ratings apply.

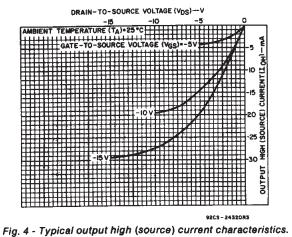








CD4504B Types



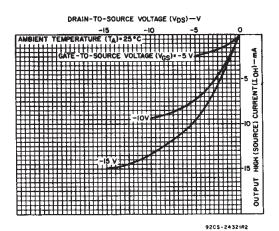


Fig. 5 - Minimum output high (source) current characteristics.

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC		LIN	UNITS	
		Min.	Max.	UNITS
Supply-Voltage Range (For T _A = Full Package-Temperature Range)	<u> </u>	3	18	V
. No. 62				

CHARACTERISTIC					LIN		
CHARACTERISTI	C I	SHIFTING MODE		VDD (V)	TYP.	TYP. MAX.	UNITS
		TTL to CMOS	5	10	140	280	
			5	15	140	280	
Propagation Delay:	ſ	CMOS to CMOS	5	10	120	240]
High-to Low,	t _{PHL}	V _{DD} > V _{CC}	5	15	120	240	
		. •	10	15	70	140	
	Γ	CMOS to CMOS	10	5	275	550	1
		Vcc>Vod	15	5	275	550	
			15	10	70	140	
		TTL to CMOS	5	10	140	280	ns
	1	$V_{DD} > V_{CC}$	5	15	140	280	
	Γ	CMOS to CMOS	5	10	120	240	1
	TPLH	V _{DD} > V _{CC}	5	15	120	240	
			10	15	70	140	
	. · · · [CMOS to CMOS	10	5	200	400	1
		V _{CC} > V _{DD}	15	5	200	400	
	5. * ²⁵		15	10	60	120	
	1. A.			5	100	200]
Transition Time,	t _{THL} ,t _{TLH}	All Modes		10	50	100	
		····		15	40	80	
Input Capacitance,	Cin	Any Input	Any Input			7.5	pF

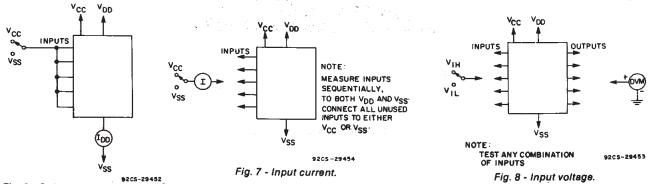
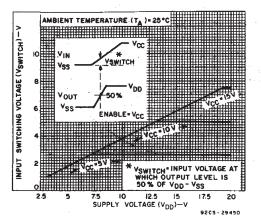
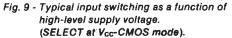


Fig. 6 - Quiescent device current.

COMMERCIAL CMOS

CD4504B Types





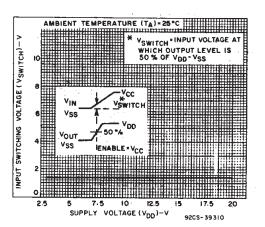
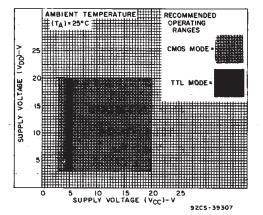
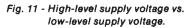
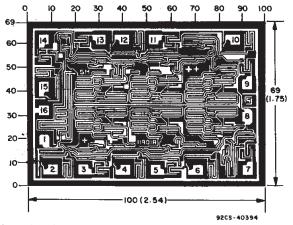


Fig. 10 - Typical input switching as a function of high-level supply voltage (SELECT at V_{SS}-TTL mode).







Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch) .

Dimensions and pad layout for CD4504BH.

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